

# A Symposium on High-Performance Chips



**Stanford University,  
Palo Alto, California**  
**August, 2009**

## Call for Contributions

### AUTHOR'S SCHEDULE

Submission due: **April 3, 2009**      Acceptance Notification: **April 27, 2009**  
Final Version due: **July 1, 2009**

### AREAS OF INTEREST:

- **General Purpose Processor Chips**
  - Low-Power
  - High-Performance
  - Multi-Core, Multi-Processor Technologies: interconnect, programming models, compiler, runtime systems
- **Other Chips**
  - Novel Technology: quantum computing, nano-structures, micro-Arrays
  - Low-power chips/Dynamic Power Management
  - Communication/Networking
  - Chipsets
  - Wireless LAN/Wireless WAN
  - FPGAs and FPGA Based Systems
  - Display Technology
- **Application-Specific / Embedded Processors**
  - Systems-on-Chip
  - Mobile Phone
  - Digital Signal Processing
  - Network/Security
  - Graphics/Multimedia/Game
- **Software:**
  - Compiler technology
  - Operating System/Chip Interaction
  - Performance Evaluation
- **Other Technologies**
  - Advanced Packaging Technology
  - Reliability and Design for Test
  - Advanced Semiconductor Process Technology

### AUTHOR INFORMATION and FORMAT

Presentations at HOT Chips are in the form of 30-minute talks using PowerPoint or .pdf. Presentation slides will be published in the HOT Chips Proceedings. Participants are not required to submit written papers, but a select group will be invited to submit a paper for inclusion in a special issue of IEEE Micro.

Submissions are evaluated by the Program Committee on the basis of performance of the device(s), degree of innovation, use of advanced technology, potential market significance, and anticipated interest to the audience. Research and software contributions will be evaluated with similar criteria.

Submissions consist of a title, extended abstract (two pages maximum), and the presenter's contact information (name, affiliation, job title, address, phone(s), fax, and email). Please indicate whether you have submitted, intend to submit, or have already presented or published a similar or overlapping submission to another conference or journal. Also indicate if you would like the submission to be held confidential.

Please submit your extended abstract in plain ASCII text by **April 3, 2009** via:  
<https://www.softconf.com/starts/hotchips21>

Submissions containing figures may be submitted in .pdf, but plain ASCII text is strongly preferred.

Send questions relating to the program to the program chairs at: [program2009@hotchips.org](mailto:program2009@hotchips.org), and send questions relating to conference operation or organization to the general chair, Keith Diefendorff, at:

[info2009@hotchips.org](mailto:info2009@hotchips.org)

Sponsored by the Technical Committee on Microprocessors and Microcomputers  
of the IEEE Computer Society and the IEEE Solid State Circuits Society



Program Committee Co-Chairs:

Krste Asanovic  
Ralph Wittig

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Check the HOT CHIPS 21 web page for updates: <http://www.hotchips.org>